

# ECSE 425 – Tutorial 1

IC Fabrication and Reliability

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# Trends in Technology

IC transistor density : 35% / year

IC die size : 10-20% / year

=> 50-55% transistors / year

RAM : 40% / year

HDD : 30% / year

Exponential growth!

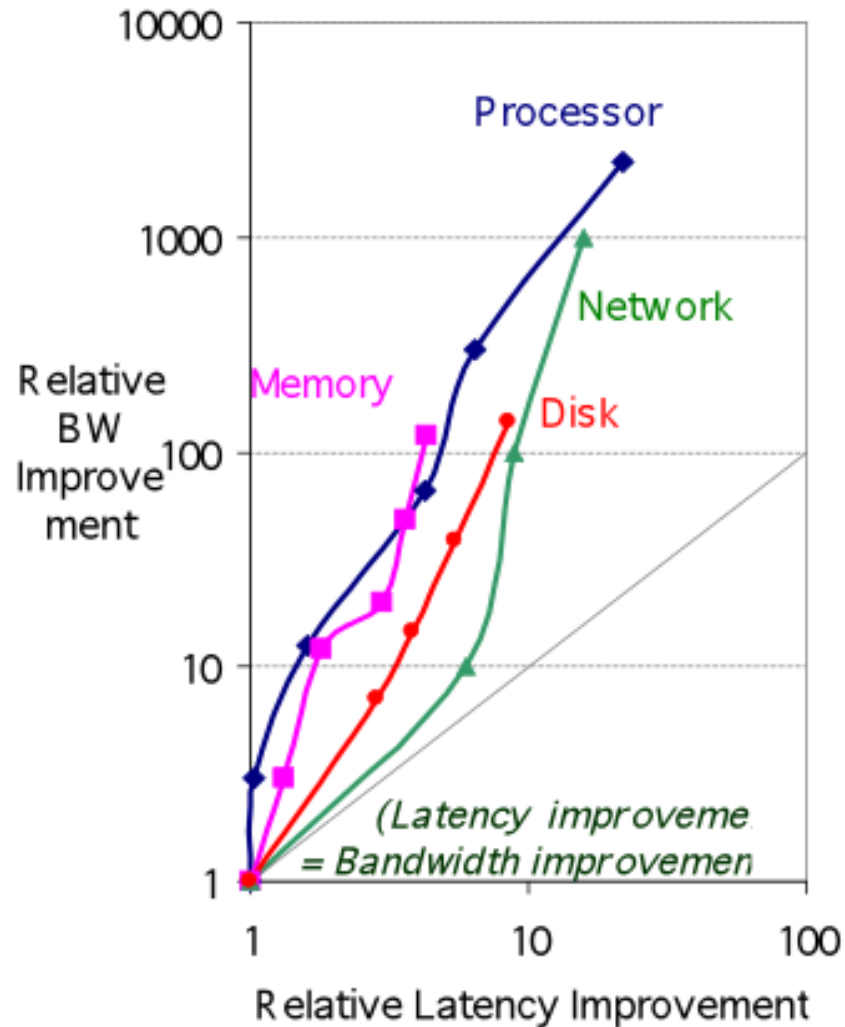


# Trends in Technology

Bandwidth : how much information you can move on average per unit time (eg: bits/sec)

Latency : how long it takes to get data once it has been requested (eg: ms)

# Trends in Technology



Bandwidth >> Latency

# Cost of an Integrated Circuit

$$(1) \quad \text{ICCost} = \frac{\text{DieCost} + \text{DieTestCost} + \text{PackagingAndTestCost}}{\text{FinalYield}}$$

$$(2) \quad \text{DieCost} = \frac{\text{WaferCost}}{\text{DiesPerWafer} \times \text{DieYield}}$$

$$(3) \quad \text{DiesPerWafer} = \frac{\pi \times \text{WaferRadius}^2}{\text{DieArea}} - \frac{\pi \times \text{WaferDiameter}}{\sqrt{2} \times \text{DieArea}}$$

$$(4) \quad \text{DieYield} = \text{WaferYield} \times \left( 1 + \frac{\text{DefectDensity} \times \text{DieArea}}{\alpha} \right)^{-\alpha}$$

# Cost of an Integrated Circuit

- Question: Number of dies per 300mm (30cm) wafer for a die that is 1.5cmx1.5cm?
  - Die area =  $2.25\text{cm}^2$
  - Dies per wafer = ...
- Find die yield under conditions above, and assuming defect density of  $0.4\text{ defect/cm}^2$  and  $\alpha=4$ .
  - Die yield = ...



# Cost of an Integrated Circuit

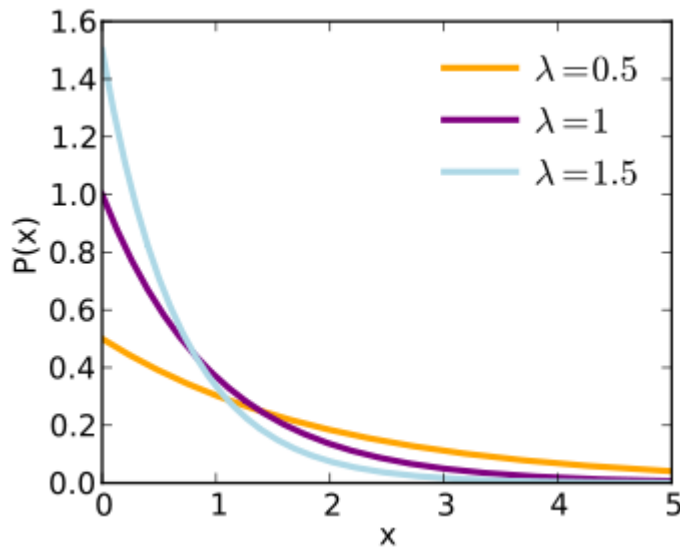
- Question:
  - a) Find the probability of a defective core in a 4-core CPU chip, assuming die area of  $3.1\text{cm}^2$ , defect rate  $0.6\text{ defect/cm}^2$ ,  $\alpha=4$ .
    - Equivalent to die yield for a die having  $\frac{1}{4}$  the area.
  - b) Find the probability that at least 3 out of 4 cores are working (so you can sell the chip as a 3-core CPU).

# Reliability

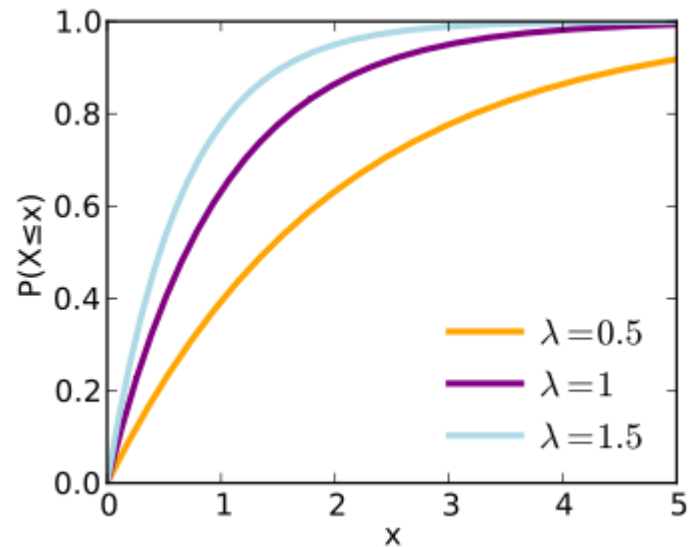
- A system with **constant failure** rate  $\lambda$  has an exponentially distributed **lifetime**  $X$ , or “time to failure”.

–  $MTTF = E[X] = 1 / \lambda$

$FIT = 10^9 \lambda$



PDF =  $\lambda e^{-\lambda x}$



CDF =  $1 - e^{-\lambda x}$

# Reliability

- If a system with lifetime  $Y$  fails whenever any of its  $n$  modules fails:
  - $Y = \min(X_1, \dots, X_n)$
  - $\lambda_{\text{system}} = \text{sum}(\lambda_i)$
  - $\text{MTTF}_{\text{system}} = E[Y] = 1 / \lambda_{\text{system}} = 1 / (\lambda_1 + \dots + \lambda_n)$

# Reliability

- MTTR: Mean time to repair
- System or Module availability =  
MTTF / (MTTF + MTTR)
- Exercise: Assume a disk subsystem with the following components and MTTF:
  - 10 disks, each rated at 1,000,000-hour MTTF
  - 1 SCSI controller, 500,00-hour MTTF
  - 1 power supply, 200,000-hour MTTF
  - 1 fan, 200,000-hour MTTF
  - 1 SCSI cable, 1,000,000-hour MTTF

$$Failure\ rate_{system} = \frac{10 \times 1}{1,000,000} + \frac{1}{500,000} + \frac{1}{200,000} + \frac{1}{200,000} + \frac{1}{1,000,000} = \frac{23,000}{1,000,000,000\ hours}$$

$$MTTF_{system} = \frac{1}{Failure\ rate_{system}} = 43,500\ hours$$